Product Change Notification: CENO-15ZDSW307

Date:

23-Feb-2026

Product Category:

Memory

Notification Subject:

CCB 8069 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for selected SST26VF016B, SST26VF016BEUI, SST26VF032B, SST26VF032BA, SST26VF032BEUI, SST25VF080B, SST25VF040B, SST26WF064C, SST26VF064B, SST26VF064BA, SST26VF064BEUI, SST25VF020B, SST25PF020B, SST26VF080A, SST26VF040A, SST26VF020A, USBF8100, SST26WF080B, SST26WF080BA, SST26WF040B, SST26WF040BA, SST26WF016B and SST26WF016BA device families available in 8L SOIC (.208in and .150in) packages at MTAI assembly site.

Affected CPNs:

CENO-15ZDSW307_Affected_CPN_02232026.pdf
CENO-15ZDSW307_Affected_CPN_02232026.csv

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for selected SST26VF016B, SST26VF016BEUI, SST26VF032B, SST26VF032BA, SST26VF032BEUI, SST25VF080B, SST25VF040B, SST26WF064C, SST26VF064B, SST26VF064BA, SST26VF064BEUI, SST25VF020B, SST25PF020B, SST26VF080A, SST26VF040A, SST26VF020A, USBF8100, SST26WF080B, SST26WF080BA, SST26WF040B, SST26WF040BA, SST26WF016B and SST26WF016BA device families available in 8L SOIC (.208in and .150in) packages at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	**Post Change**	Change (Yes/No)
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	8390A (PFAS Free)	QMI519 (PFAS Free)	Yes
Molding Compound Material	G600V	G600V	No
Lead-Frame Material	CDA194	CDA194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: April 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	February 2026				**>**	**April 2026**				
Work Week	06	07	08	09		14	15	16	17	28
Initial PCN Issue Date				X						
Qual Report Availability						X				
Final PCN Issue Date						X				

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:

February 23, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CENO-15ZDSW307_Qual Plan.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

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